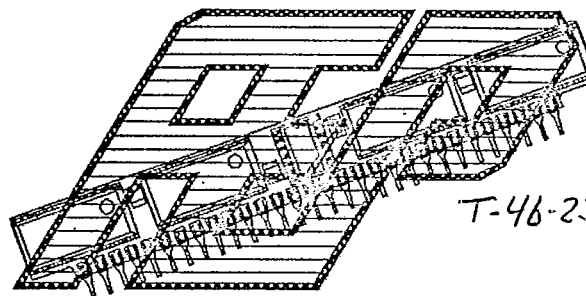


- >> 4,194,304 x 9 Organization
- >> 30 pin SIP
- >> Low 0.510 inch stand-off height
- >> Optional PARITY CHECKER on board
- >> Single +5V power supply
- >> TTL compatible
- >> Pin for pin compatible with standard modules
(without parity checker)
- >> Available in 1M x 9 organization



T-46-23-18

4 MEGAWORD BY 9 BIT LOW PROFILE DYNAMIC RAM MODULE WITH PARITY CHECKER

DESCRIPTION:

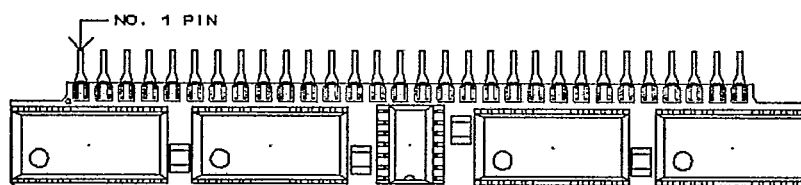
The AEPDX4M9L is a low profile 4,194,304 megaword by 9 bit dynamic random access memory module in a 30 pin single in-line package format. Physically it consists of an FR4 PC material substrate mounted with nine 4M x 1 SOJ (small outline J-leaded package) ICs, the 74F280 parity checker, four 0.18 microfarad capacitors, and 30 edge clip I/O pins.

The module can use any of the 4M x 1 SOJs available from multiple manufacturers in both NMOS and low power CMOS technologies and with a variety of access speeds.

Power dissipation is also determined by the ICs used but is typically 50 milliwatts in standby and 2.5 to 3.5 watts when active (ratings for the CMOS version without the parity checker). A single 5V power supply is required.

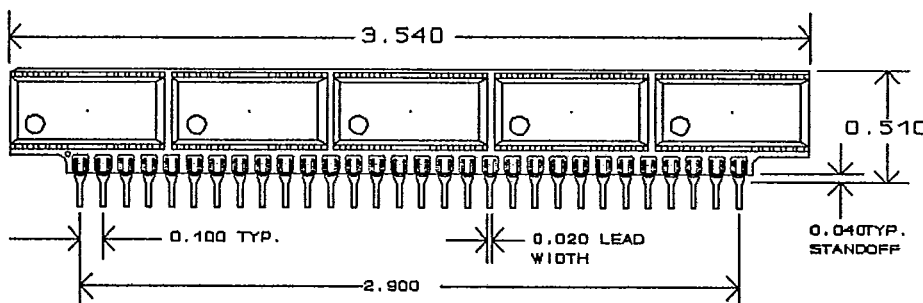
Variations available are a 4M x 9 without the parity checker (making it compatible with standard 4M x 9 modules); or any of these with 90 degree lead pins, allowing them to be mounted on their sides thus giving a 0.350 stand-off height.

SPECIFICATION DRAWING 4Mx9 LOW PROFILE DRAM WITH PARITY CHECKER - 30 PIN SIP

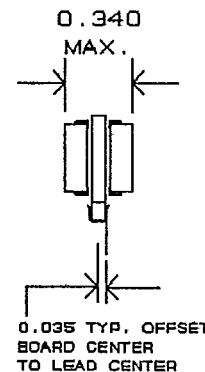


REAR VIEW

DIMENSIONS
IN INCHES,
TOLERANCE:
+/- 0.010



FRONT VIEW



SIDE VIEW



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4 MEGABYTE x 9 LOW PROFILE DYNAMIC RAM MODULE

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SIP PIN OUT CONFIGURATION

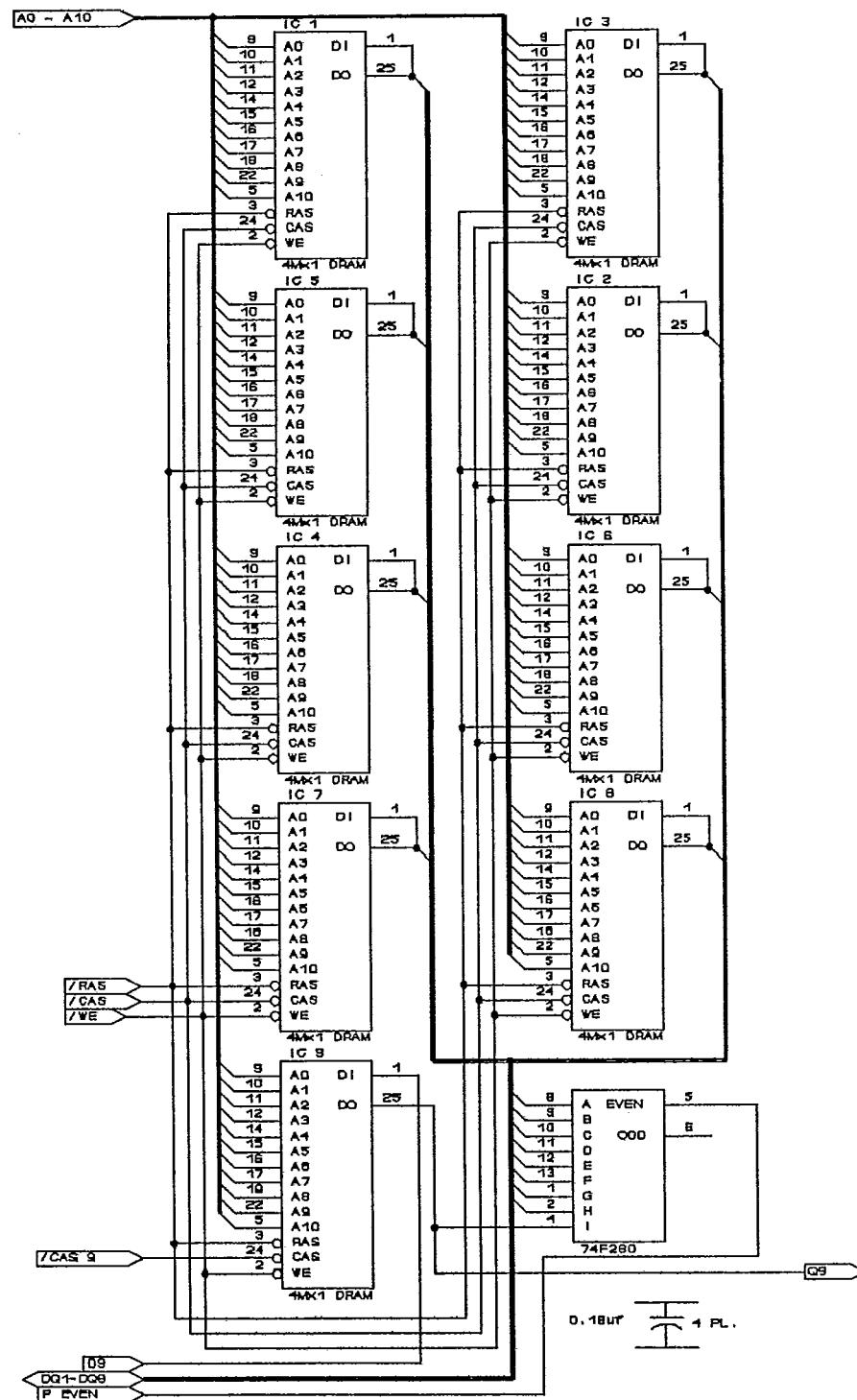
FUNCTIONAL DIAGRAM

1	VCC
2	CAS*
3	DQ ₁
4	A ₀
5	A ₁
6	DQ ₂
7	A ₂
8	A ₃
9	VSS
10	DQ ₃
11	A ₄
12	A ₅
13	DQ ₄
14	A ₆
15	A ₇
16	DQ ₅
17	A ₈
18	A ₉
19	PEVEN**
20	DQ ₆
21	WE*
22	VSS
23	DQ ₇
24	A ₁₀ ***
25	DQ ₈
26	Q ₉
27	RAS*
28	CAS ₉ *
29	D ₉
30	VCC

* ACTIVE WHEN LOW

** NO CONNECT WHEN
OPTIONAL PARITY CHECKER
IS OMITTED.

*** ANC FOR 1M x 9 MODULE.



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